ABSTRACT

PUNCH SINGULATION SYSTEM AND METHOD

A punching system for singulating IC units comprising: a punching assembly arranged to receive a substrate and singulate said substrate into the IC units; a rotary carrier rotatable from a first position to a second position said rotary carrier arranged to receive said units at the first position and carry said units to the second position through rotation; wherein said rotary carrier includes recesses for receiving at least a portion of the units.

Figure 1